

GP-1 Cu Heavy Bonding Wire for Power Device

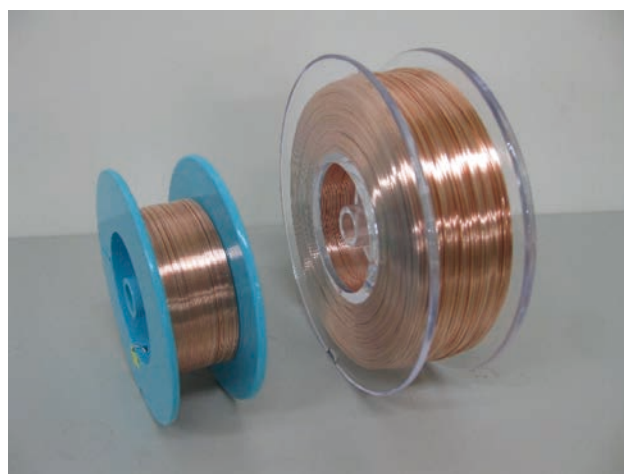
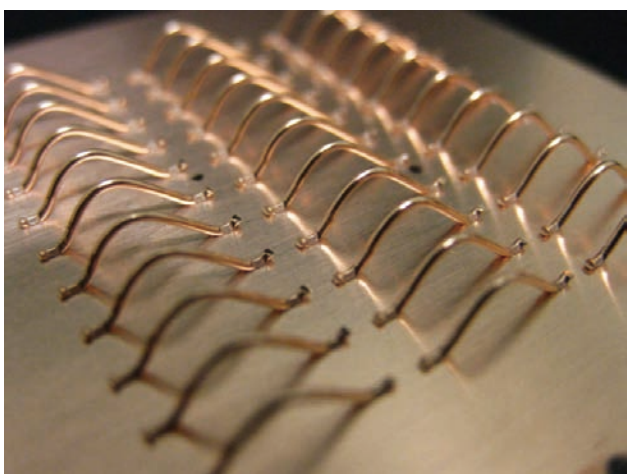
パワーデバイス用Cuボンディングワイヤ

Characteristics

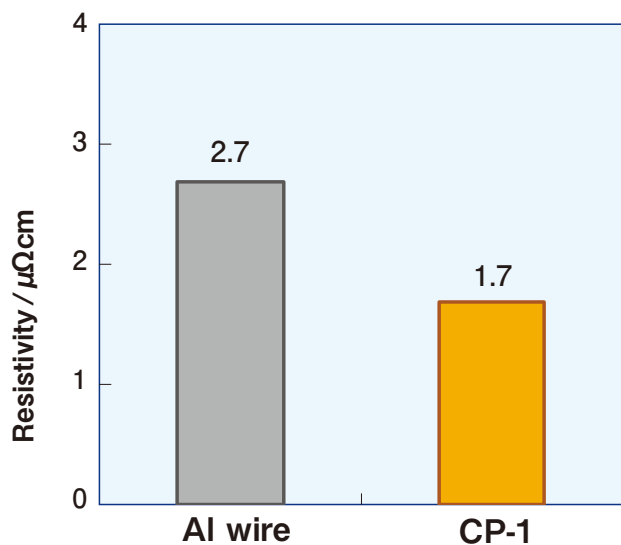
- Excellent electrical conductivity (40% higher than Al)
- High fusing current (30% higher than Al)
- Available diameter (ϕ 100~500 μ m)

特 徴

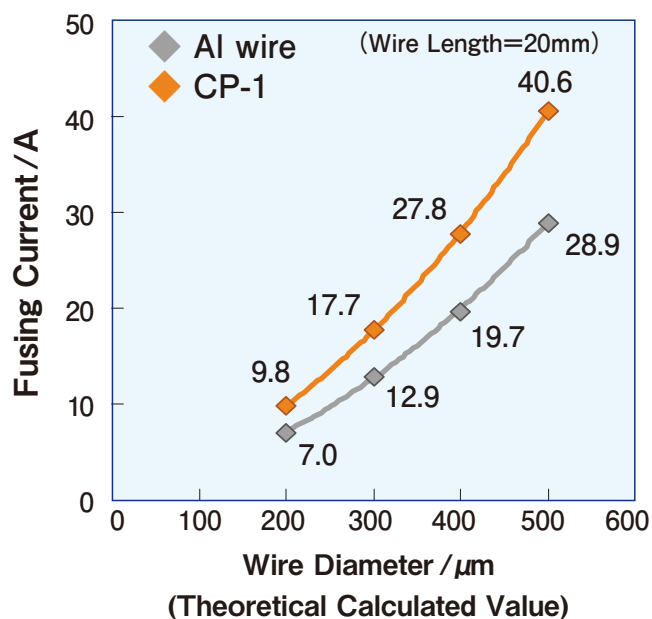
- 優れた電気伝導性 (40% higher than Al)
- 優れた溶断電流 (30% higher than Al)
- 対応線径 (ϕ 100~500 μ m)



Resistivity



Fusing Current



CP-1 Data Sheet

General Properties

Wire Diameter (um)	100	125	150	200	250	300	350	380	400	450	500	
Tolerance (um)	+/- 5.0			+/- 7.0							+/- 10.0	
Breaking Load (gf)	102-305	153-356	255-560	510-917	816-1427	1326-2039	1734-2651	2040-3059	2346-3365	3264-4282	4079-5302	
Elongation (%)	5.0 - 35.0						10.0 - 40.0				10.0-50.0	
maximum winding length (m)	300										200	

Physical Property

Hardness (HV)	Wire	60 - 80									
Density (g/cm ³)	8.92										
Resistivity (u Ω cm) @ 20°C	1.7										
Fusing Current (A, Length=10mm,10sec)	2.2	3.4	4.9	8.8	14	20	27	32	35	44	55
Electrical resistance (mΩ, Length 10mm, Room Temp.)	21.9 - 26.8	14.3 - 16.8	10.1 - 11.5	5.6 - 6.5	3.7 - 4.1	2.6 - 2.8	1.9 - 2.1	1.6 - 1.7	1.5 - 1.6	1.2	0.9 - 1.0
Thermal Conductivity @ 20°C (W/m/K)	385										
Linear Expansion Coefficient (0-100°C) (ppm/K)	17.0										
Elastic Modulus (GPa)	80 - 100										
Melting Point (°C)	1,083										